FOR$^2$ENSiCS

## Speakers and their titles for

# Summer School on Next-Generation Power Semiconductors for Power Electronics

## 29/06 Topic: Semiconductor devices for Power Electronics

9-9:15 Welcome and plan for the day

9:15- 10:15 Speaker: Dr N. Donato (University of Cambridge)
Title “***The journey of SiC from MOSFET to UHV IGBTs***”

10:15-10:30 Coffee break

10:30-11:30 Speaker: Prof. M. Antoniou (University of Warwick)
Title **“Advanced 3D MOS Cell Design Concepts for SiC MOSFETs”**

11:30-12:30 Speaker: Dr. N. Kipfel (Hitachi Energy)
Title **“Power module packaging, how to adapt the best technology to the need of the client?”**

12:30-14 Lunch break

14:00-15:00 Speaker: Dr. A. Schoner (RISE)
**Title “Advanced Epitaxial Material enabling the Fabrication of UHV SiC Power Devices”**

15-16:30 Networking and round table session led by Katie Hore, Innovation Director, REWIRE

## 30/06 Topic: Power converters and systems

9-9:15 Welcome and plan for the day

9:15- 10:15 Speaker: Prof. Drazen Djuic (EPFL)
**Title "Solid State Transformers: An Overview, Challenges and Opportunities"**

10:15-10:30 Coffee break

10:30-11:30 Speaker: Dr Besar Asslani (SuperGrid)
**Title "Solid State Transformer and Associated Technologies for future MVDC networks"**

10:30-11:30 Speaker: Prof. P. Godignon
**Title "Life cycle analysis of SiC devices" technologies"**

11:30-12:30 Speaker: F. Beg (Cambridge GaN Devices)
**Title "The Coexistence Decade: GaN, SiC, and the Power Conversion Stack behind AI"**

12:30-14 Lunch break

14-16:30 Poster session (**Committee will select 3 best for poster award**)

## 01/07 Topic: Package and reliability of power devices

9-9:15 Welcome and plan for the day

9:15- 10:15 Speaker: Marcel Dinse (University of Bremen)
**Title "Testing of Wide Band-Gap Power devices"**

10:15-10:30 Coffee break

10:30-11:30 Speaker: Dr P. Evans (Nottingham University)
**Title "Modelling and Virtual Prototypes for Power Electronic Design"**

11:30-12:30 Speaker: Dr. P. Laserre (Deep Concept)
**Title "Power module packaging, how to adapt the best technology to the need of the client?"**

12:30-14 Lunch break

**14-14:15 Final remarks/Closing**